

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Tsuga et al. Docket No: TI-31621
Serial No: TBD Examiner: TBD
Filed: 02/28/02 Art Unit: TBD
For: METHOD AND DEVICE FOR REMOVING PARTICLES ON SEMICONDUCTOR WAFERS

CLAIM FOR PRIORITY FROM FOREIGN APPLICATION UNDER 35 U.S.C. §119

Assistant Commissioner For Patents
Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on 2-28-02

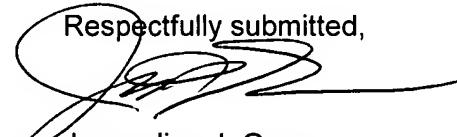
Marianna Smith

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I hereby claim foreign priority benefits under 35 U.S.C. §119(a)-(d) or (f), or 365(b) of any foreign application(s) for patent, inventor's or plant breeder's rights certificate(s), or 365(a) of any PCT International application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent, inventor's or plant breeder's rights certificate(s), or any PCT international application having a filing date before that of the application which priority is claimed.

| Prior Foreign Application Number(s) | Country | Foreign Filing Date | Priority Not Claimed | Certified Copy Attached? |
|-------------------------------------|---------|---------------------|--------------------------|--|
| 13(2001)-59777 | Japan | 03/05/2001 | <input type="checkbox"/> | <input type="checkbox"/> <input checked="" type="checkbox"/> |

Respectfully submitted,


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